



# SOT136-1

plastic small outline package; 28 leads; body width 7.5 mm

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	SO28
<b>Package type industry code</b>	SO28
<b>Package style descriptive code</b>	SO (small outline)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>IEC package outline code</b>	075E06
<b>JEDEC package outline code</b>	MS-013
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	19-2-2003

Table 1. Package summary

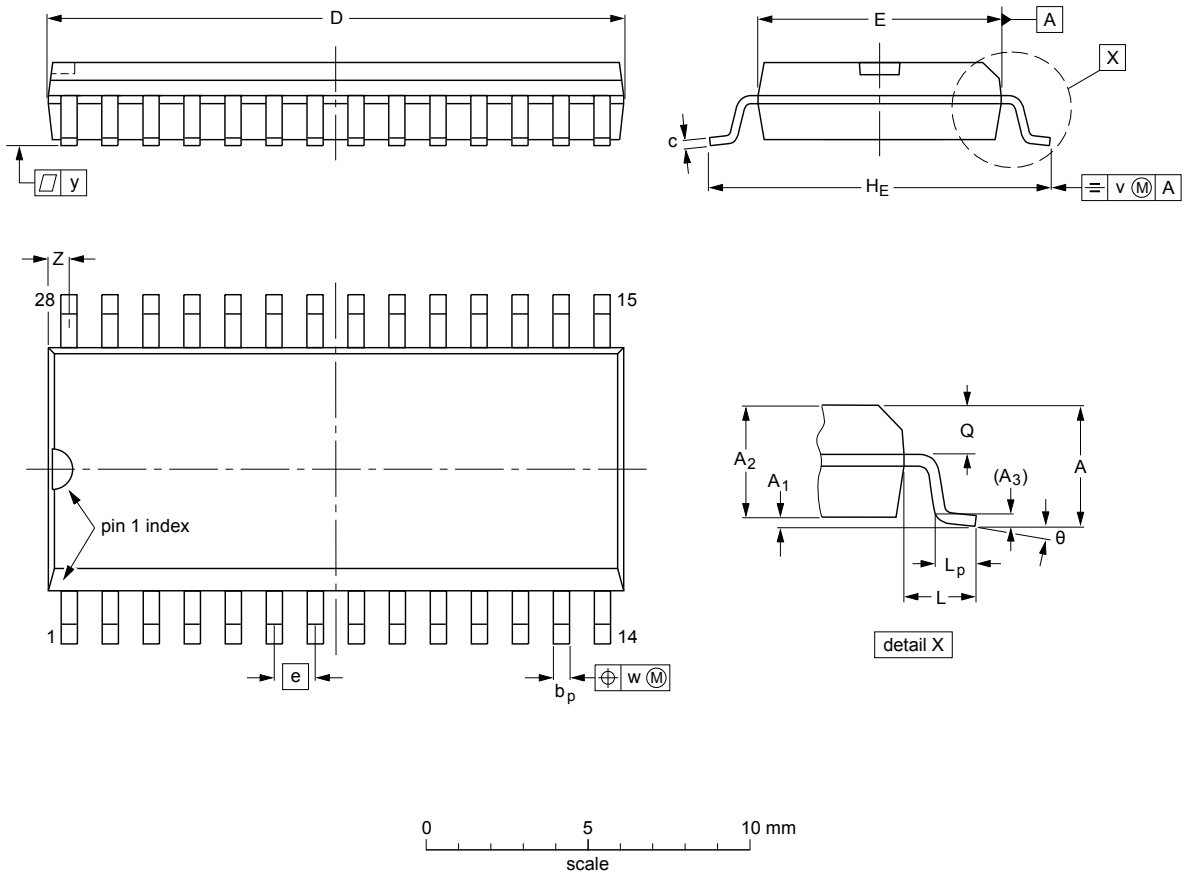
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	17.7	-	17.9	18.1	mm
E	package width	7.4	-	7.5	7.6	mm
A	seated height	[tbd]	-	2.65	2.65	mm
A <sub>2</sub>	package height	2.25	-	2.35	2.45	mm
n <sub>2</sub>	actual quantity of termination	-	-	28	-	



2. Package outline

SO28: plastic small outline package; 28 leads; body width 7.5 mm

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DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	H <sub>E</sub>	L	L <sub>p</sub>	Q	v	w	y	Z <sup>(1)</sup>	θ
mm	2.65	0.3 0.1	2.45 2.25	0.25	0.49 0.36	0.32 0.23	18.1 17.7	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8° 0°
inches	0.1	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.71 0.69	0.30 0.29	0.05	0.419 0.394	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	

Note

1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT136-1	075E06	MS-013			99-12-27 03-02-19

Fig. 1. Package outline SO28 (SOT136-1)

### 3. Soldering

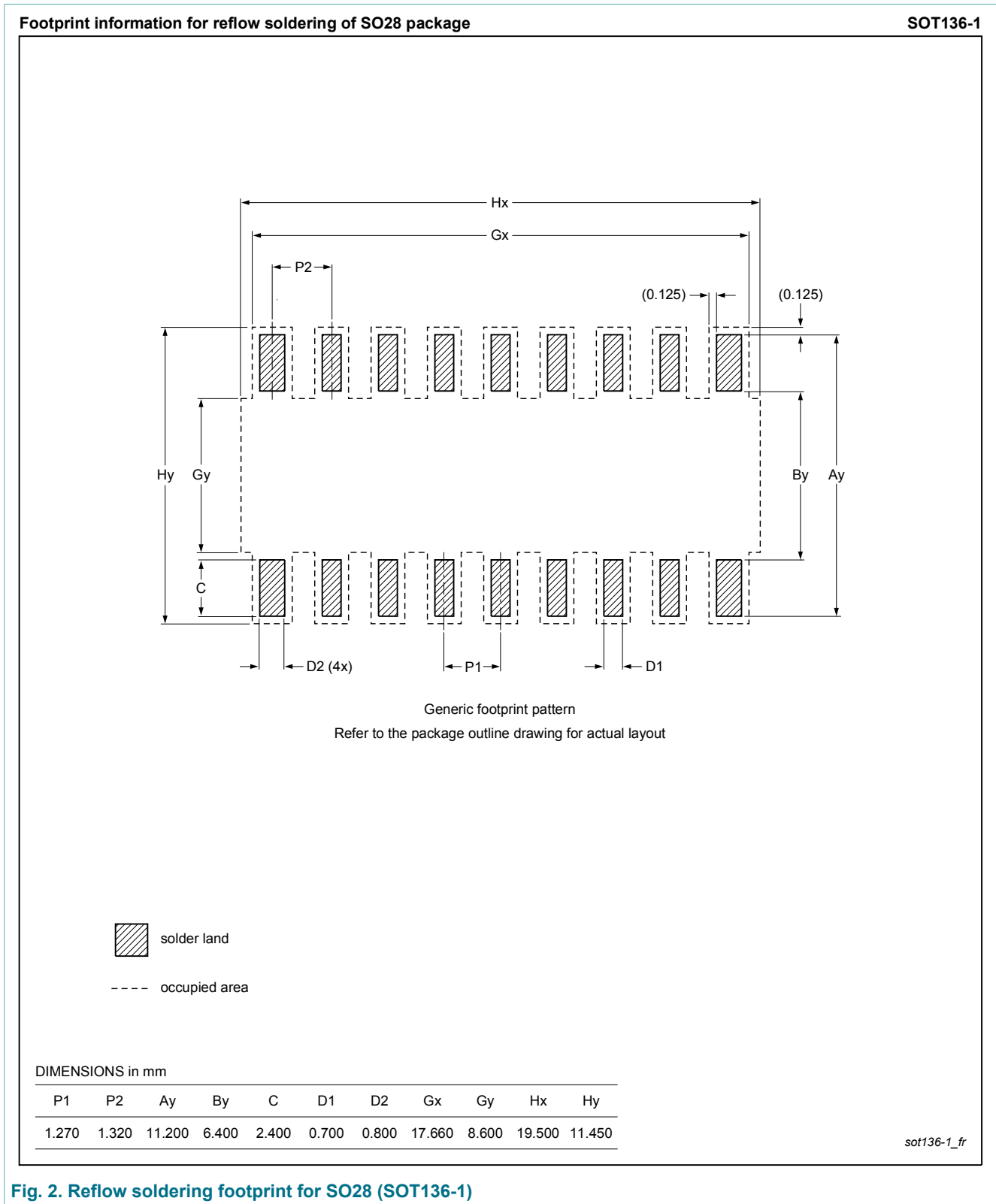


Fig. 2. Reflow soldering footprint for SO28 (SOT136-1)

plastic small outline package; 28 leads; body width 7.5 mm

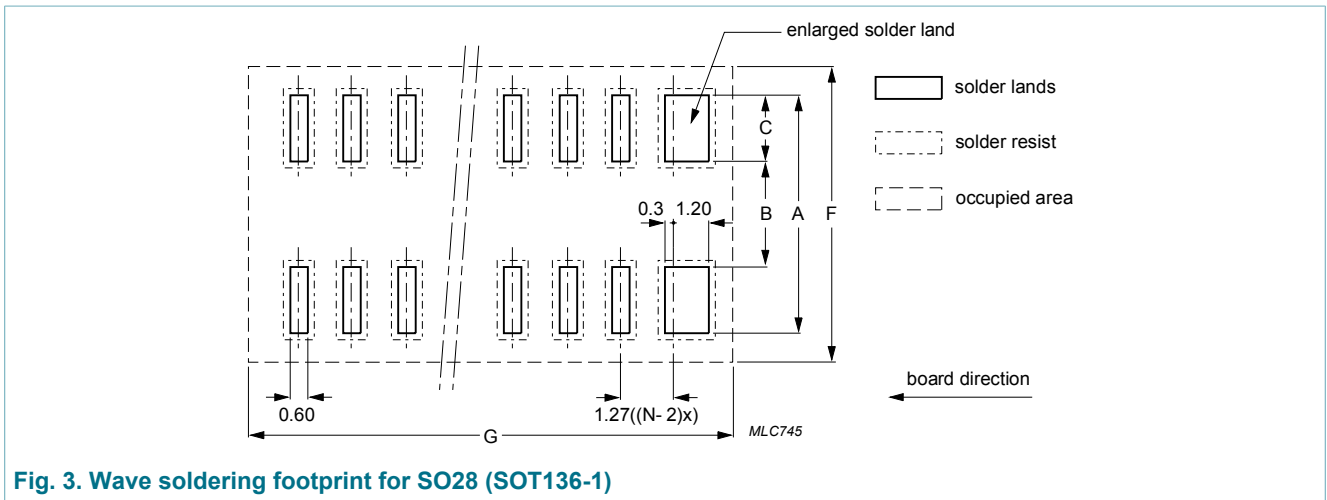


Fig. 3. Wave soldering footprint for SO28 (SOT136-1)

## 4. Legal information

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